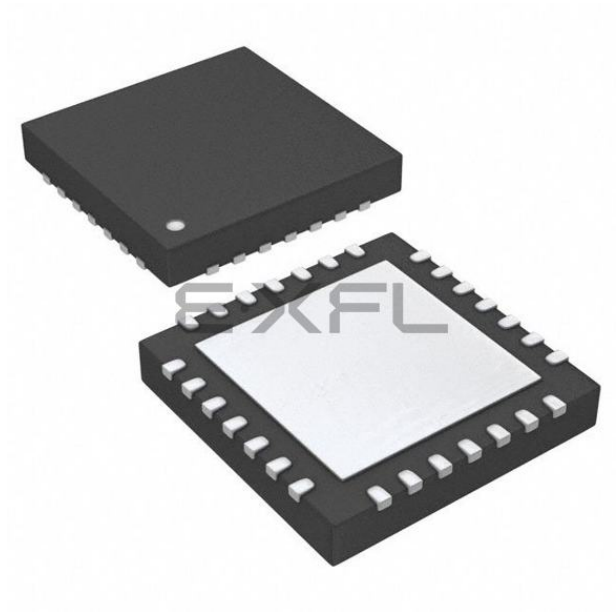
Microchip Technology - PIC24FV32KA302-I/ML Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv32ka302-i-ml

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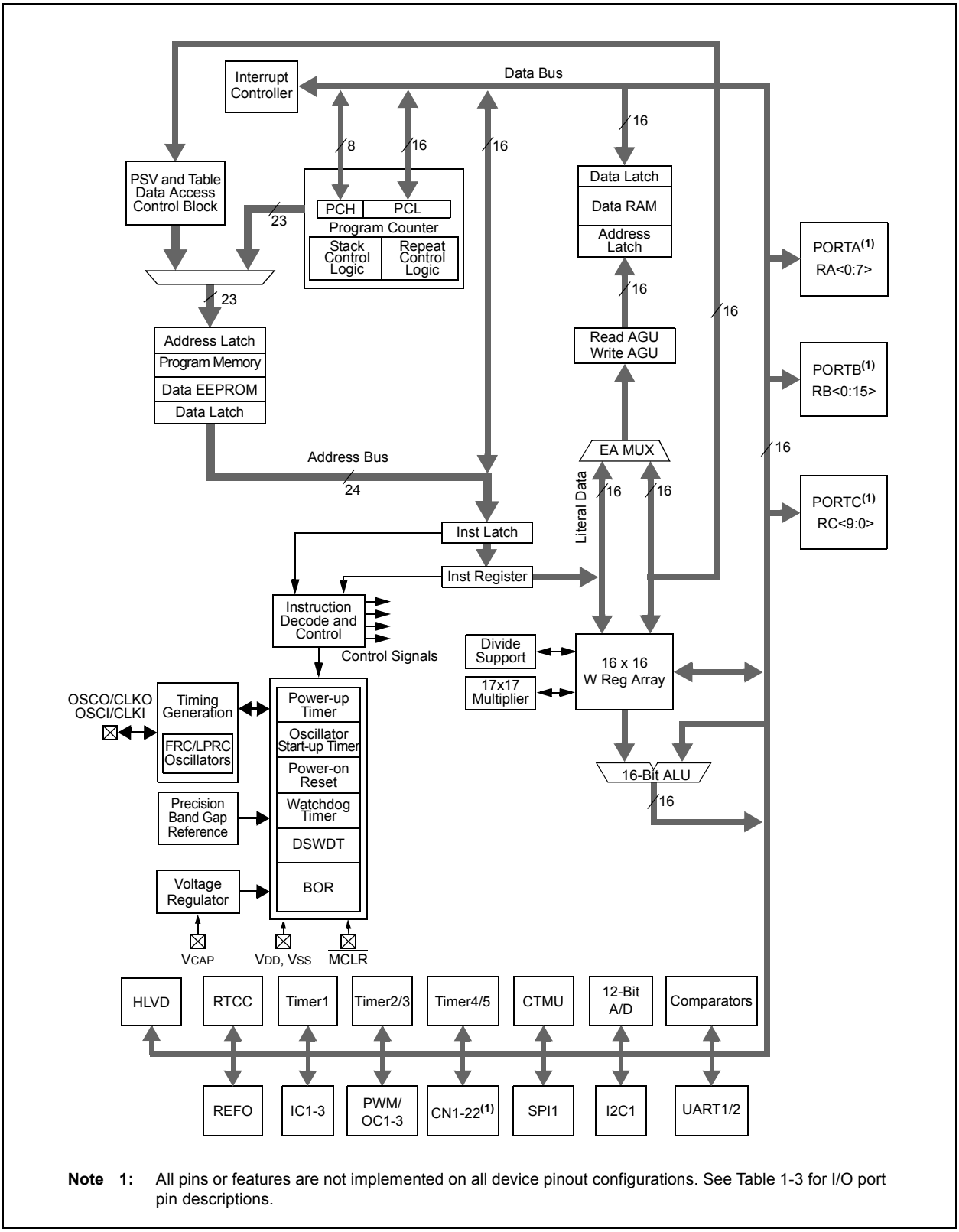
FIGURE 1-1: PIC24FV32KA304 FAMILY GENERAL BLOCK DIAGRAM



Note 1: All pins or features are not implemented on all device pinout configurations. See Table 1-3 for I/O port pin descriptions.

2.6 External Oscillator Pins

Many microcontrollers have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 9.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Place the oscillator circuit close to the respective oscillator pins with no more than 0.5 inch (12 mm) between the circuit components and the pins. The load capacitors should be placed next to the oscillator itself, on the same side of the board.

Use a grounded copper pour around the oscillator circuit to isolate it from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed.

Layout suggestions are shown in Figure 2-5. In-line packages may be handled with a single-sided layout that completely encompasses the oscillator pins. With fine-pitch packages, it is not always possible to completely surround the pins and components. A suitable solution is to tie the broken guard sections to a mirrored ground layer. In all cases, the guard trace(s) must be returned to ground.

In planning the application's routing and I/O assignments, ensure that adjacent port pins and other signals, in close proximity to the oscillator, are benign (i.e., free of high frequencies, short rise and fall times, and other similar noise).

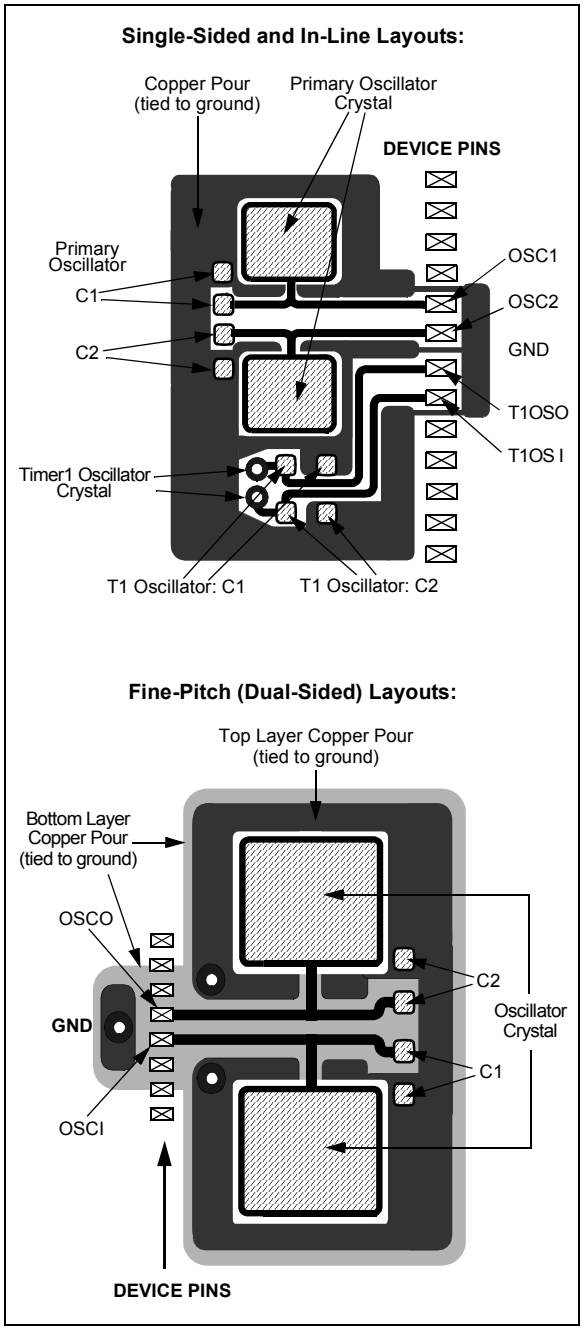
For additional information and design guidance on oscillator circuits, please refer to these Microchip Application Notes, available at the corporate web site (www.microchip.com):

- *AN826, "Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"*
- *AN849, "Basic PICmicro® Oscillator Design"*
- *AN943, "Practical PICmicro® Oscillator Analysis and Design"*
- *AN949, "Making Your Oscillator Work"*

2.7 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state. Alternatively, connect a 1 kΩ to 10 kΩ resistor to Vss on unused pins and drive the output to logic low.

FIGURE 2-5: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



NOTES:

REGISTER 7-1: RCON: RESET CONTROL REGISTER(1)

R/W-0, HS	R/W-0, HS	R/W-0	R/W-0	U-0	R/C-0, HS	R/W-0	R/W-0
TRAPR	IOPUWR	SBOREN	RETEN(3)	—	DPSLP	CM	PMSLP
bit 15							bit 8

R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-1, HS	R/W-1, HS
EXTR	SWR	SWDTEN(2)	WDTO	SLEEP	IDLE	BOR	POR
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or Uninitialized W register used as an Address Pointer caused a Reset
0 = An illegal opcode or Uninitialized W Reset has not occurred

bit 13 **SBOREN:** Software Enable/Disable of BOR bit
1 = BOR is turned on in software
0 = BOR is turned off in software

bit 12 **RETEN:** Retention Sleep Mode control bit(3)
1 = Regulated voltage supply provided solely by the Retention Regulator (RETEN) during Sleep
0 = Regulated voltage supply provided by the main Voltage Regulator (VREG) during Sleep

bit 11 **Unimplemented:** Read as '0'

bit 10 **DPSLP:** Deep Sleep Mode Flag bit
1 = Deep Sleep has occurred
0 = Deep Sleep has not occurred

bit 9 **CM:** Configuration Word Mismatch Reset Flag bit
1 = A Configuration Word Mismatch Reset has occurred
0 = A Configuration Word Mismatch Reset has not occurred

bit 8 **PMSLP:** Program Memory Power During Sleep bit
1 = Program memory bias voltage remains powered during Sleep
0 = Program memory bias voltage is powered down during Sleep and the Voltage Regulator enters Standby mode

bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset (Instruction) Flag bit
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed

Note 1: All of the Reset status bits may be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTENx Configuration bit is '1' (unprogrammed), the WDT is always enabled regardless of the SWDTEN bit setting.

3: This is implemented on PIC24FV32KA3XX parts only; not used on PIC24F32KA3XX devices.

REGISTER 8-1: SR: ALU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R-0, HSC
—	—	—	—	—	—	—	DC(1)
bit 15							bit 8

R/W-0, HSC	R/W-0, HSC	R/W-0, HSC	R-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC
IPL2(2,3)	IPL1(2,3)	IPL0(2,3)	RA(1)	N(1)	OV(1)	Z(1)	C(1)
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)

111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

Note 1: See Register 3-1 for the description of these bits, which are not dedicated to interrupt control functions.

2: The IPL<2:0> bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the Interrupt Priority Level if IPL3 = 1.

3: The IPLx Status bits are read-only when NSTDIS (INTCON1<15>) = 1.

Note: Bit 8 and bits 4 through 0 are described in **Section 3.0 "CPU"**.

REGISTER 11-2: ANSB: ANALOG SELECTION (PORTB)

R/W-1	R/W-1	R/W-1	R/W-1	U-0	U-0	U-0	U-0
ANSB15	ANSB14	ANSB13	ANSB12	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	ANSB4	ANSB3(1)	ANSB2	ANSB1	ANSB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **ANSB<15:12>:** Analog Select Control bits
1 = Digital input buffer is not active (use for analog input)
0 = Digital input buffer is active

bit 11-5 **Unimplemented:** Read as '0'

bit 4-0 **ANSB<4:0>:** Analog Select Control bits(1)
1 = Digital input buffer is not active (use for analog input)
0 = Digital input buffer is active

Note 1: The ANSB3 bit is not available on 20-pin devices.

REGISTER 11-3: ANSC ANALOG SELECTION (PORTC)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
—	—	—	—	—	ANSC2(1)	ANSC1(1)	ANSC0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as '0'

bit 2-0 **ANSC<2:0>:** Analog Select Control bits(1)
1 = Digital input buffer is not active (use for analog input)
0 = Digital input buffer is active

Note 1: These bits are not available on 20-pin or 28-pin devices.

REGISTER 13-2: TyCON: TIMER3 AND TIMER5 CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON(1)	—	TSIDL(1)	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0
—	TGATE(1)	TCKPS1(1)	TCKPS0(1)	—	—	TCS(1)	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TON:** Timery On bit(1)
1 = Starts 16-bit Timery
0 = Stops 16-bit Timery

bit 14 **Unimplemented:** Read as '0'

bit 13 **TSIDL:** Timery Stop in Idle Mode bit(1)
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **TGATE:** Timery Gated Time Accumulation Enable bit(1)
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timery Input Clock Prescale Select bits(1)
11 = 1:256
10 = 1:64
01 = 1:8
00 = 1:1

bit 3-2 **Unimplemented:** Read as '0'

bit 1 **TCS:** Timery Clock Source Select bit(1)
1 = External clock is from the T3CK pin (on the rising edge)
0 = Internal clock (FOSC/2)

bit 0 **Unimplemented:** Read as '0'

Note 1: When 32-bit operation is enabled (TxCON<3> = 1), these bits have no effect on Timery operation. All timer functions are set through the TxCON register.

REGISTER 15-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits(1)

111 = Center-Aligned PWM mode on OCx
110 = Edge-Aligned PWM mode on OCx
101 = Double Compare Continuous Pulse mode: Initialize OCx pin low; toggle OCx state continuously on alternate matches of OCxR and OCxRS
100 = Double Compare Single-Shot mode: Initialize OCx pin low; toggle OCx state on matches of OCxR and OCxRS for one cycle
011 = Single Compare Continuous Pulse mode: Compare events continuously toggle the OCx pin
010 = Single Compare Single-Shot mode: Initialize OCx pin high; compare event forces the OCx pin low
001 = Single Compare Single-Shot mode: Initialize OCx pin low, compare event forces the OCx pin high
000 = Output compare channel is disabled

Note 1: The comparator module used for Fault input varies with the OCx module. OC1 and OC2 use Comparator 1; OC3 and OC4 use Comparator 2; OC5 uses Comparator 3.

REGISTER 15-2: OCxCON2: OUTPUT COMPARE x CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
FLTMD	FLTOUT	FLTTRIEN	OCINV	—	DCB1(3)	DCB0(3)	OC32
bit 15							bit 8

R/W-0	R/W-0, HS	R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0
OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FLTMD:** Fault Mode Select bit
1 = Fault mode is maintained until the Fault source is removed and the corresponding OCFLTx bit is cleared in software
0 = Fault mode is maintained until the Fault source is removed and a new PWM period starts

bit 14 **FLTOUT:** Fault Out bit
1 = PWM output is driven high on a Fault
0 = PWM output is driven low on a Fault

bit 13 **FLTTRIEN:** Fault Output State Select bit
1 = Pin is forced to an output on a Fault condition
0 = Pin I/O condition is unaffected by a Fault

bit 12 **OCINV:** Output Compare x Invert bit
1 = OCx output is inverted
0 = OCx output is not inverted

bit 11 **Unimplemented:** Read as '0'

bit 10-9 **DCB<1:0>:** Output Compare x Pulse-Width Least Significant bits(3)
11 = Delays OCx falling edge by 3/4 of the instruction cycle
10 = Delays OCx falling edge by 1/2 of the instruction cycle
01 = Delays OCx falling edge by 1/4 of the instruction cycle
00 = OCx falling edge occurs at the start of the instruction cycle

bit 8 **OC32:** Cascade Two Output Compare Modules Enable bit (32-bit operation)
1 = Cascade module operation is enabled
0 = Cascade module operation is disabled

bit 7 **OCTRIG:** Output Compare x Sync/Trigger Select bit
1 = Triggers OCx from source designated by the SYNCSELx bits
0 = Synchronizes OCx with source designated by the SYNCSELx bits

bit 6 **TRIGSTAT:** Timer Trigger Status bit
1 = Timer source has been triggered and is running
0 = Timer source has not been triggered and is being held clear

bit 5 **OCTRIS:** Output Compare x Output Pin Direction Select bit
1 = OCx pin is tri-stated
0 = Output Compare x peripheral is connected to the OCx pin

Note 1: Do not use an output compare module as its own trigger source, either by selecting this mode or another equivalent SYNCSELx setting.

2: Use these inputs as trigger sources only and never as Sync sources.

3: These bits affect the rising edge when OCINV = 1. The bits have no effect when the OCMx bits (OCxCON1<2:0>) = 001.

EQUATION 16-1: RELATIONSHIP BETWEEN DEVICE AND SPIx CLOCK SPEED(1)

$$FSCK = \frac{FCY}{\text{Primary Prescaler} * \text{Secondary Prescaler}}$$

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

TABLE 16-1: SAMPLE SCKx FREQUENCIES(1,2)

FCY = 16 MHz		Secondary Prescaler Settings				
		1:1	2:1	4:1	6:1	8:1
Primary Prescaler Settings	1:1	Invalid	8000	4000	2667	2000
	4:1	4000	2000	1000	667	500
	16:1	1000	500	250	167	125
	64:1	250	125	63	42	31
FCY = 5 MHz						
Primary Prescaler Settings	1:1	5000	2500	1250	833	625
	4:1	1250	625	313	208	156
	16:1	313	156	78	52	39
	64:1	78	39	20	13	10

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

2: SCKx frequencies are indicated in kHz.

REGISTER 17-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	AMSK9	AMSK8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK7	AMSK6	AMSK5	AMSK4	AMSK3	AMSK2	AMSK1	AMSK0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as '0'

bit 9-0 **AMSK<9:0>:** Mask for Address Bit x Select bits

1 = Enables masking for bit x of an incoming message address; bit match is not required in this position

0 = Disables masking for bit x; bit match is required in this position

REGISTER 17-4: PADCFG1: PAD CONFIGURATION CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	—	SMBUSDEL2	SMBUSDEL1	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5 **SMBUSDEL2:** SMBus SDA2 Input Delay Select bit

1 = The I2C2 module is configured for a longer SMBus input delay (nominal 300 ns delay)

0 = The I2C2 module is configured for a legacy input delay (nominal 150 ns delay)

bit 4 **SMBUSDEL1:** SMBus SDA1 Input Delay Select bit

1 = The I2C1 module is configured for a longer SMBus input delay (nominal 300 ns delay)

0 = The I2C1 module is configured for a legacy input delay (nominal 150 ns delay)

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	R/W-0, HC	R/W-0	R-0, HSC	R-1, HSC
UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN	UTXBF	TRMT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-1, HSC	R-0, HSC	R-0, HSC	R/C-0, HS	R-0, HSC
URXISEL1	URXISEL0	ADDEN	RIDLE	PERR	FERR	OERR	URXDA
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
HS = Hardware Settable bit	C = Clearable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15,13 **UTXISEL<1:0>:** UARTx Transmission Interrupt Mode Selection bits
- 11 = Reserved; do not use
- 10 = Interrupt when a character is transferred to the Transmit Shift Register (TSR) and as a result, the transmit buffer becomes empty
- 01 = Interrupt when the last character is shifted out of the Transmit Shift Register; all transmit operations are completed
- 00 = Interrupt when a character is transferred to the Transmit Shift Register (this implies there is at least one character open in the transmit buffer)

bit 14 **UTXINV:** IrDA® Encoder Transmit Polarity Inversion bit

If IREN = 0:
- 1 = UxTX Idle '0'
- 0 = UxTX Idle '1'

If IREN = 1:
- 1 = UxTX Idle '1'
- 0 = UxTX Idle '0'

bit 12 **Unimplemented:** Read as '0'

bit 11 **UTXBRK:** UARTx Transmit Break bit
- 1 = Sends Sync Break on next transmission – Start bit, followed by twelve '0' bits, followed by Stop bit; cleared by hardware upon completion
- 0 = Sync Break transmission is disabled or completed

bit 10 **UTXEN:** UARTx Transmit Enable bit
- 1 = Transmit is enabled; UxTX pin is controlled by UARTx
- 0 = Transmit is disabled; any pending transmission is aborted and the buffer is reset. UxTX pin is controlled by the PORT register.

bit 9 **UTXBF:** UARTx Transmit Buffer Full Status bit (read-only)
- 1 = Transmit buffer is full
- 0 = Transmit buffer is not full, at least one more character can be written

bit 8 **TRMT:** Transmit Shift Register Empty bit (read-only)
- 1 = Transmit Shift Register is empty and the transmit buffer is empty (the last transmission has completed)
- 0 = Transmit Shift Register is not empty; a transmission is in progress or queued

bit 7-6 **URXISEL<1:0>:** UARTx Receive Interrupt Mode Selection bits
- 11 = Interrupt is set on a RSR transfer, making the receive buffer full (i.e., has 4 data characters)
- 10 = Interrupt is set on a RSR transfer, making the receive buffer 3/4 full (i.e., has 3 data characters)
- 0x = Interrupt is set when any character is received and transferred from the RSR to the receive buffer; receive buffer has one or more characters.

REGISTER 25-2: CTMUCON2: CTMU CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **EDG1MOD:** Edge 1 Edge-Sensitive Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 14 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge 1 is programmed for a positive edge response
0 = Edge 1 is programmed for a negative edge response

bit 13-10 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1111 = Edge 1 source is Comparator 3 output
1110 = Edge 1 source is Comparator 2 output
1101 = Edge 1 source is Comparator 1 output
1100 = Edge 1 source is IC3
1011 = Edge 1 source is IC2
1010 = Edge 1 source is IC1
1001 = Edge 1 source is CTED8
1000 = Edge 1 source is CTED7
0111 = Edge 1 source is CTED6
0110 = Edge 1 source is CTED5
0101 = Edge 1 source is CTED4
0100 = Edge 1 source is CTED3**(2)**
0011 = Edge 1 source is CTED1
0010 = Edge 1 source is CTED2
0001 = Edge 1 source is OC1
0000 = Edge 1 source is Timer1

bit 9 **EDG2STAT:** Edge 2 Status bit
Indicates the status of Edge 2 and can be written to control the current source.
1 = Edge 2 has occurred
0 = Edge 2 has not occurred

bit 8 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control the current source.
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 7 **EDG2MOD:** Edge 2 Edge-Sensitive Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

Note 1: Edge sources, CTED11 and CTED12, are not available on PIC24FV32KA302 devices.
2: Edge sources, CTED3, CTED11, CTED12 and CTED13, are not available on PIC24FV32KA301 devices.

TABLE 29-20: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
OS50	FPLLI	PLL Input Frequency Range	4	—	8	MHz	ECPLL, HSPLL modes, -40°C ≤ TA ≤ +85°C
OS51	FSYS	PLL Output Frequency Range	16	—	32	MHz	-40°C ≤ TA ≤ +85°C
OS52	TLOCK	PLL Start-up Time (Lock Time)	—	1	2	ms	
OS53	DCLK	CLKO Stability (Jitter)	-2	1	2	%	Measured over a 100 ms period

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 29-21: AC CHARACTERISTICS: INTERNAL RC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
F20	**Internal FRC Accuracy @ 8 MHz(1)**						
	FRC	-2	—	+2	%	+25°C	3.0V ≤ VDD ≤ 3.6V, F device 3.2V ≤ VDD ≤ 5.5V, FV device
		-5	—	+5	%	-40°C ≤ TA ≤ +85°C	1.8V ≤ VDD ≤ 3.6V, F device 2.0V ≤ VDD ≤ 5.5V, FV device
	LPRC @ 31 kHz(2)						
F21		-15	—	15	%		

Note 1: Frequency is calibrated at +25°C and 3.3V. The OSCTUN bits can be used to compensate for temperature drift.

2: The change of LPRC frequency as VDD changes.

TABLE 29-22: INTERNAL RC OSCILLATOR SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
	TFRC	FRC Start-up Time	—	5	—	μs	
	TLPRC	LPRC Start-up Time	—	70	—	μs	

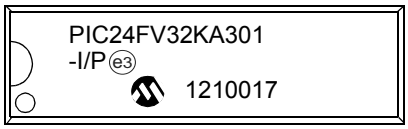
Note 1: These parameters are characterized but not tested in manufacturing.

31.0 PACKAGING INFORMATION

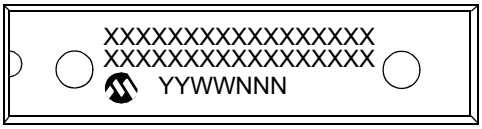
31.1 Package Marking Information

20-Lead PDIP (300 mil)

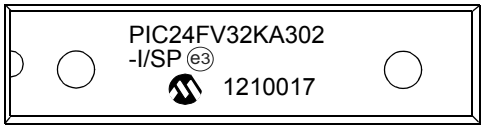
Example



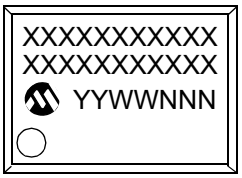
28-Lead SPDIP (.300")



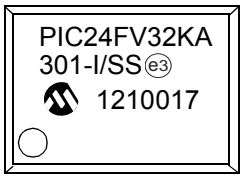
Example



20-Lead SSOP (5.30 mm)



Example



28-Lead SSOP (5.30 mm)

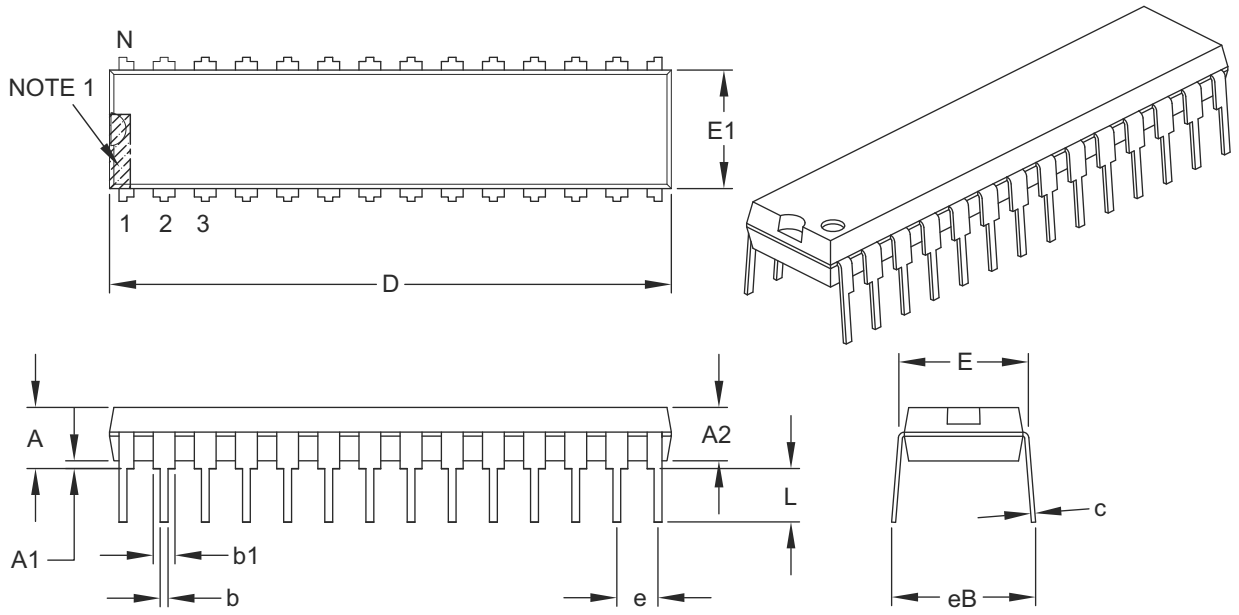
Example

Legend:	XX...X	Product-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

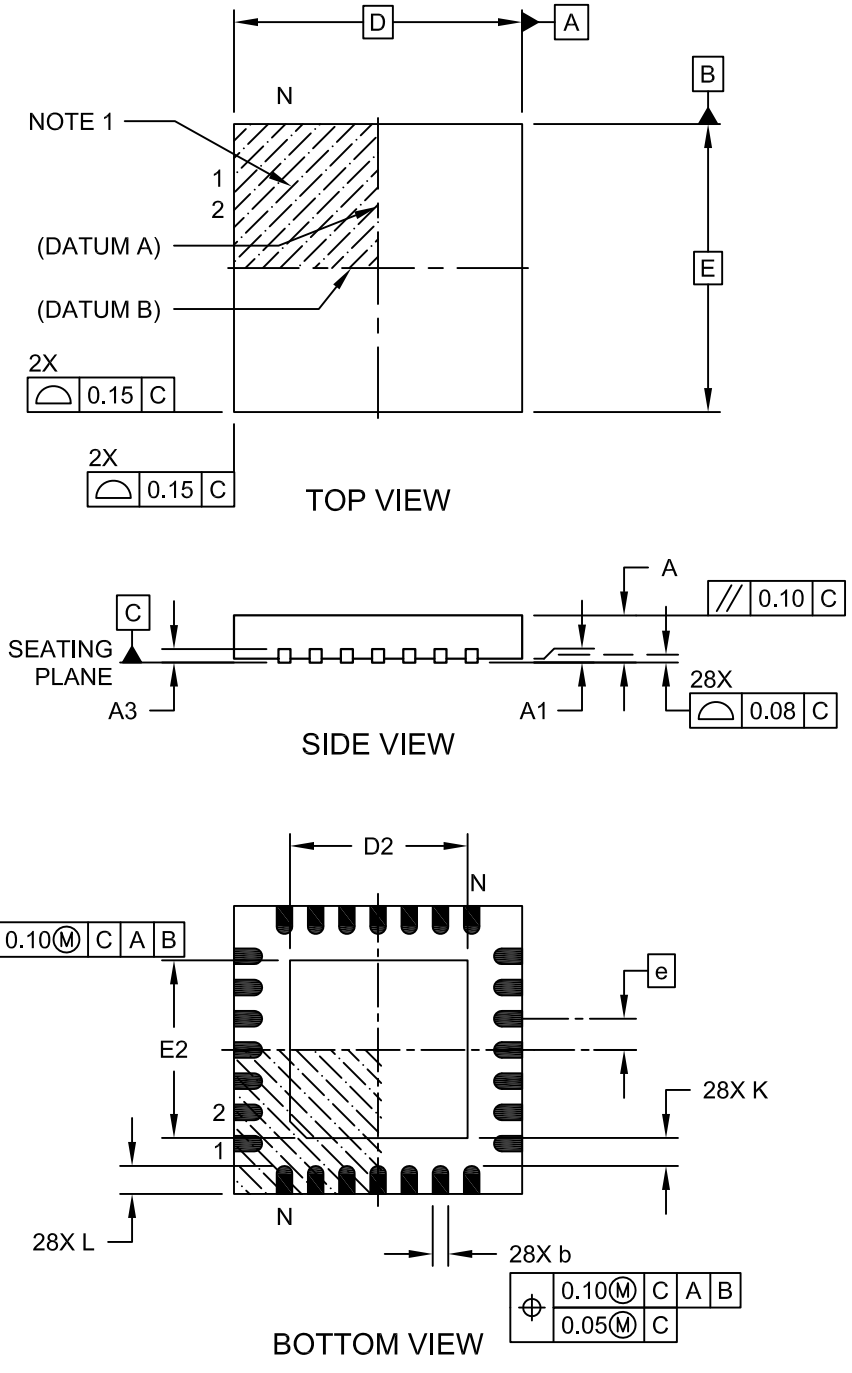
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN]
With 0.55 mm Terminal Length

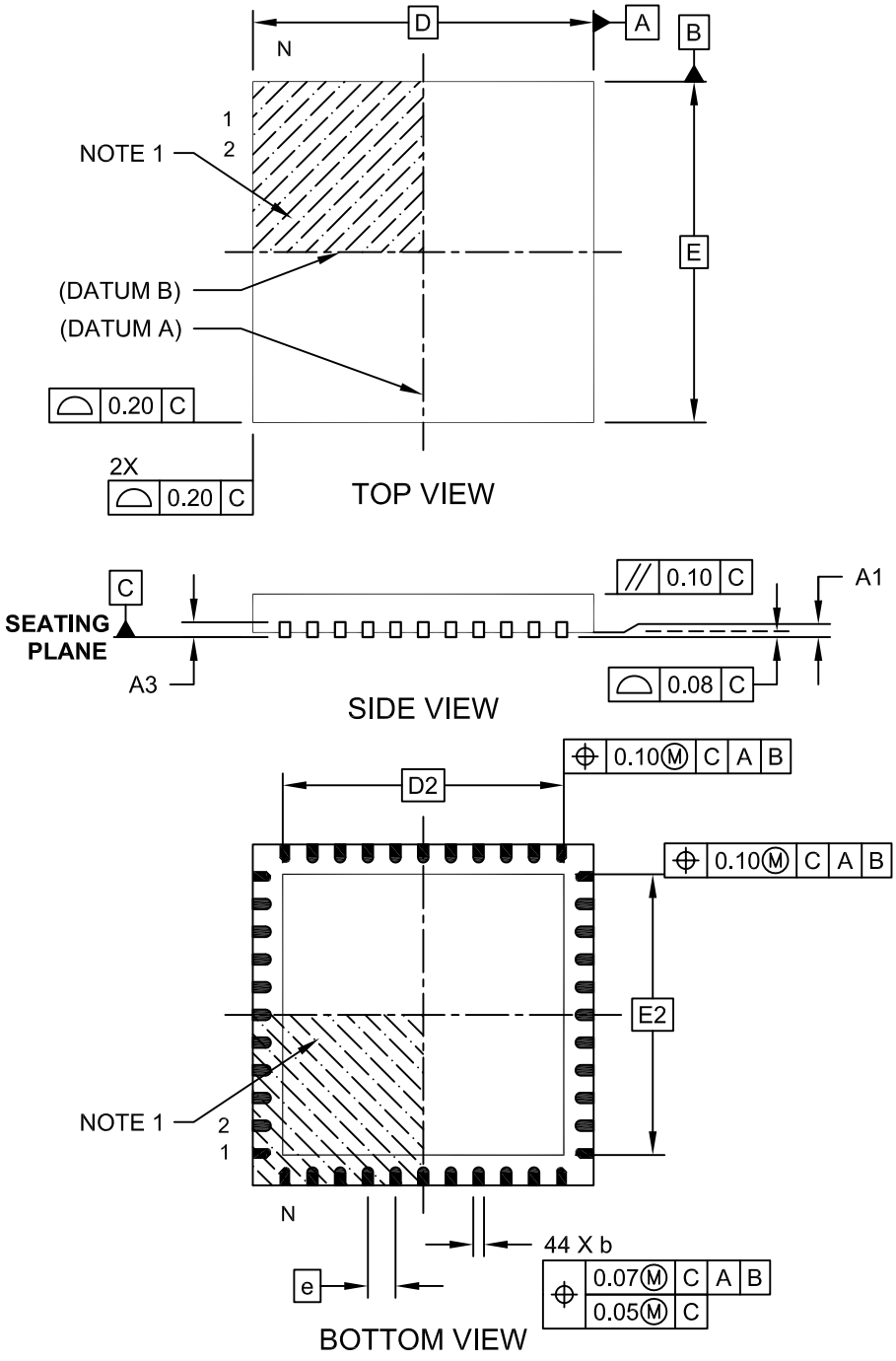
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-105C Sheet 1 of 2

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-103C Sheet 1 of 2

Revision D (March 2013)

Throughout the data sheet: corrected the name of RCON register bit 12 as RETEN, to maintain consistency with other PIC24F devices (was previously LVREN). In addition, changed the description of the bit in the RCON register (Register 7-1) to clarify its function in controlling the Retention Regulator.

Throughout the data sheet: corrected the name of FPOR Configuration register bit 2 as RETCFG, to maintain consistency with other PIC24F devices (was previously LVRCFG). In addition, changed the description of the bit in the FPOR Configuration register (Register 26-6) to clarify its function in enabling the Retention Regulator.

For **Section 10.4 "Voltage Regulator-Based Power-Saving Features"**:

- Removed all references to Fast Wake-up Sleep mode, not implemented in this device
- Changed all references of the High-Voltage Regulator to On-Chip Voltage Regulator
- Removed all references to the Low-Voltage Regulator, which was replaced in most cases with Retention Regulator
- Clarified the Retention Regulator's operation in **Section 10.4.3 "Retention Sleep Mode"** (formerly "Low-Voltage Sleep Mode")
- Modified Table 10-1 for consistency with the above changes

Corrects **Section 26.2 "On-Chip Voltage Regulator"** to clarify the operation of the on-chip regulator in "F" and "FV" families, and include DC parameters and specifications.

For **Section 29.0 "Electrical Characteristics"**:

- Updated captioning on all specification tables to include extended temperature data
- Amended Table 29-8 to include +125°C data for all existing specifications
- Added new Table 29-27 and Figure 29-8 to characterize external clock input specifications for general purpose timers (all subsequent tables and figures are renumbered accordingly)
- Added parameter numbers to several existing but previous unnumbered parameters in multiple tables

Updated **Section 30.0 "DC and AC Characteristics Graphs and Tables"**:

- Added additional graphs for Extended temperature devices (**Section 30.2 "Characteristics for Extended Temperature Devices (-40°C to +125°C)"**, Figure 30-40 through Figure 30-56)
- Replaced Figure 30-32 with an updated graph

Replaced some of the packaging diagrams in **Section 31.0 "Packaging Information"** with the newly revised diagrams.

Updates Product Information System to include extended temperature devices in the information key.

Other minor typographic corrections throughout.